

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

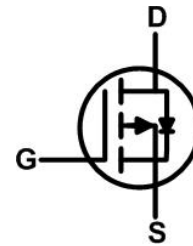
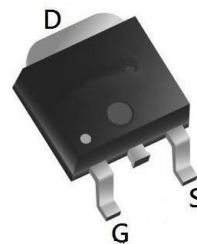
**Product Summary**


BVDSS	R <sub>DS(on)</sub>	I <sub>D</sub>
-40V	1.0 mΩ	-52A

**Description**

The 50P04 is the high cell density trenched P-ch MOSFETs, which provide excellent R<sub>DS(on)</sub> and gate charge for most of the synchronous buck converter applications.

The 50P04 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**TO252 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-52	A
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, -V <sub>GS</sub> @ -10V <sup>1</sup>	-35	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-160	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	144	mJ
I <sub>AS</sub>	Avalanche Current	-30.0	A
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	45	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	3.6	°C/W

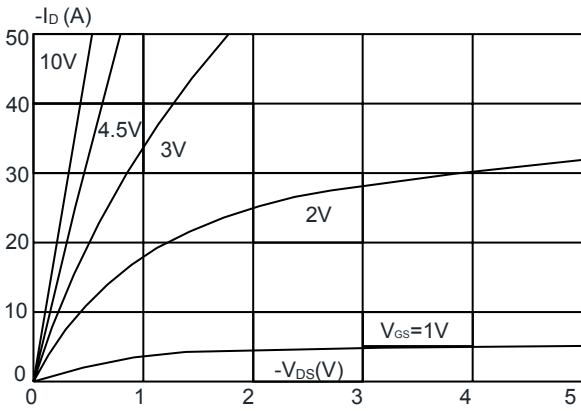
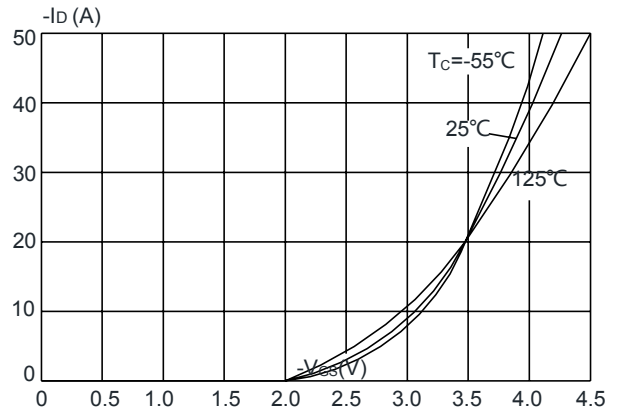
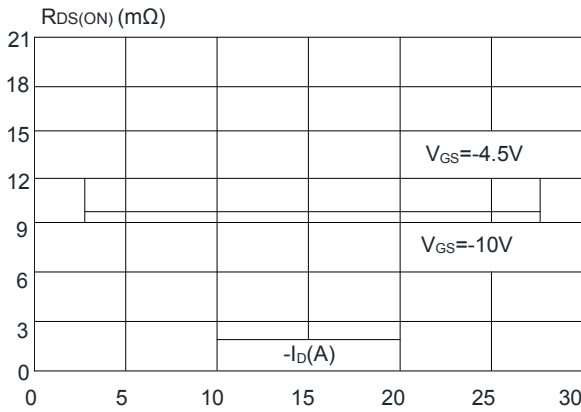
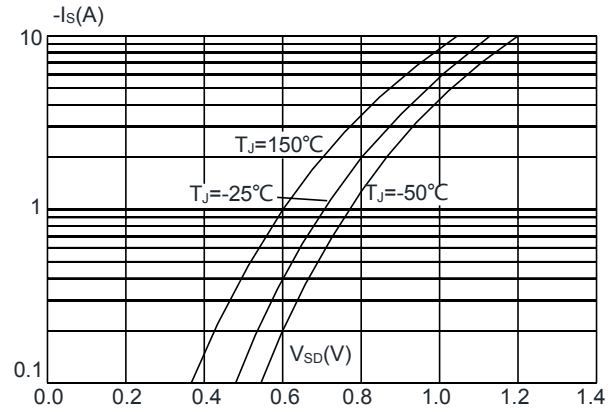
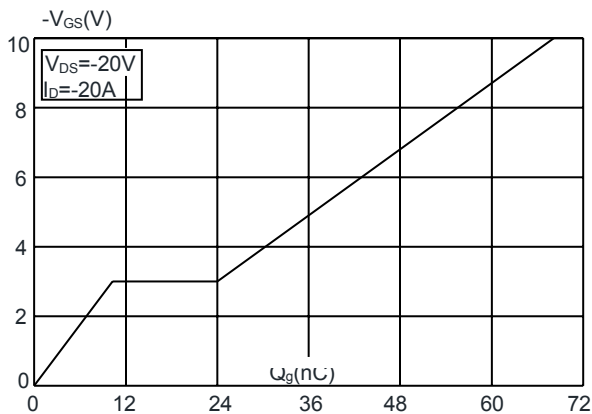
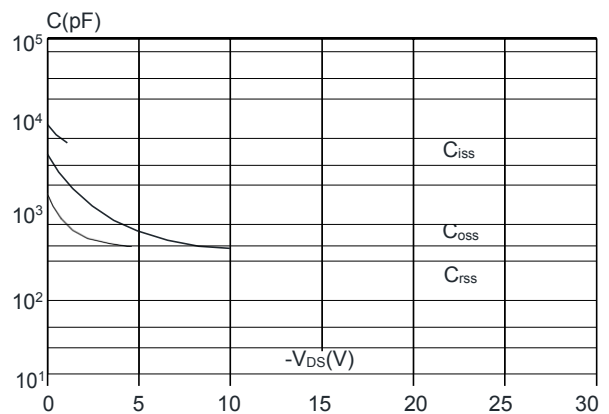
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-40	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-40V, V_{GS}=0V$	-	-	-1	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0	-1.7	-2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance <small>note3</small>	$V_{GS}=-10V, I_D=-20A$	-	10	13	m $\Omega$
		$V_{GS}=-4.5V, I_D=-10A$	-	15	22	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=-20V, V_{GS}=0V,$ $f=1.0MHz$	-	3800	-	pF
$C_{oss}$	Output Capacitance		-	329	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	289	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=-20V, I_D=-20A,$ $V_{GS}=-10V$	-	68	-	nC
$Q_{gs}$	Gate-Source Charge		-	10	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	14	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-20V, I_D=-20A,$ $V_{GS}=-10V, R_{GEN}=2.4\Omega$	-	10	-	ns
$t_r$	Turn-on Rise Time		-	82	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	93	-	ns
$t_f$	Turn-off Fall Time		-	74	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	-40	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-160	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=-30A$	-	-0.8	-1.2	V
$t_{rr}$	Reverse Recovery Time	$V_{GS}=0V, I_S=-30A,$ $di/dt=100A/\mu s$	-	20	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	13	-	nC

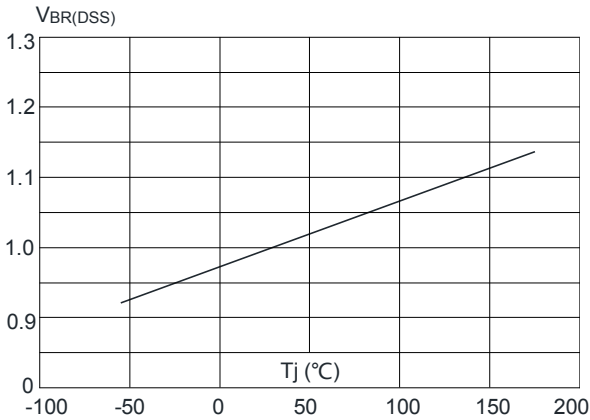
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=-20V$ ,  $V_G=-10V$ ,  $L=0.5mH$ ,  $R_G=25\Omega$ ,  $I_{AS}=-24A$

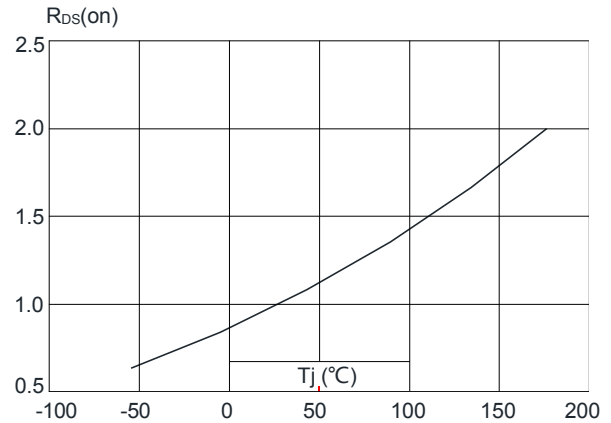
3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 2\%$

**Typical Performance Characteristics**
**Figure 1: Output Characteristics**

**Figure 2: Typical Transfer Characteristics**

**Figure 3: On-resistance vs. Drain Current**

**Figure 4: Body Diode Characteristics**

**Figure 5: Gate Charge Characteristics**

**Figure 6: Capacitance Characteristics**


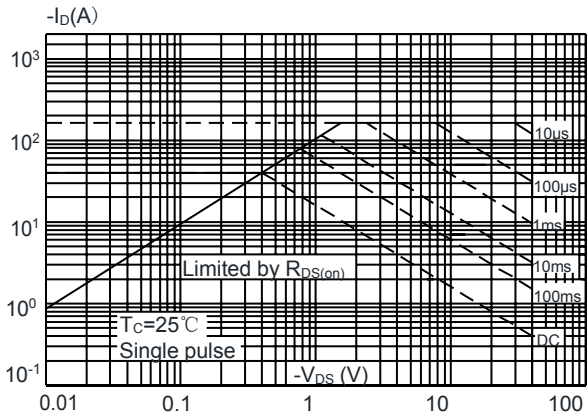
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



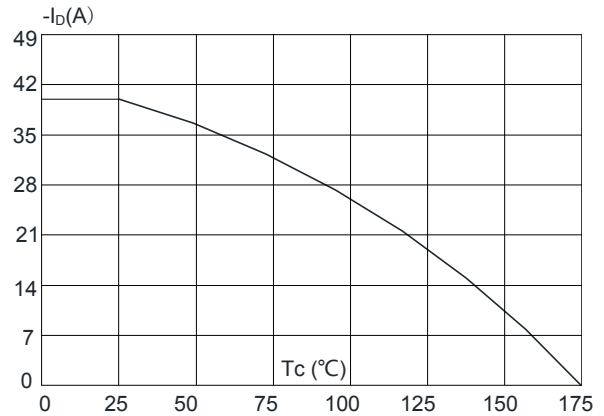
**Figure 8:** Normalized on Resistance vs. Junction Temperature



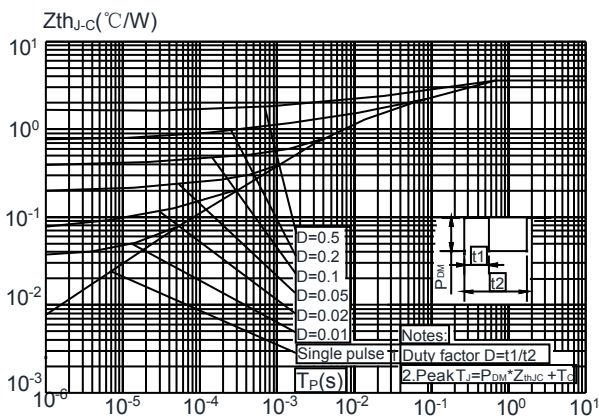
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature

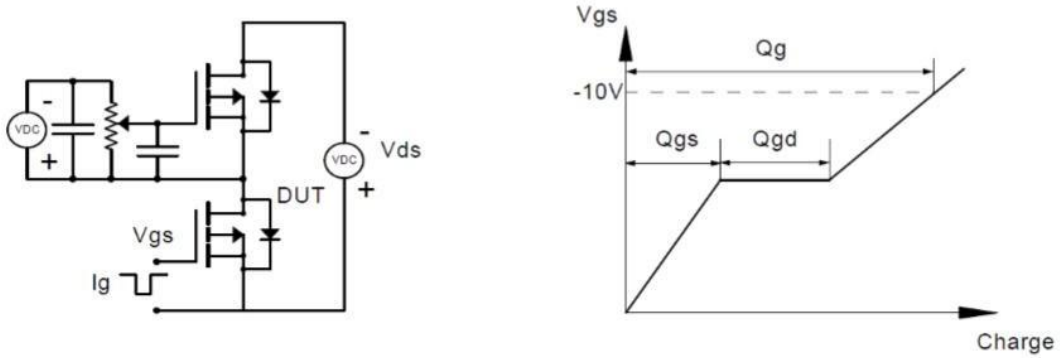


**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case

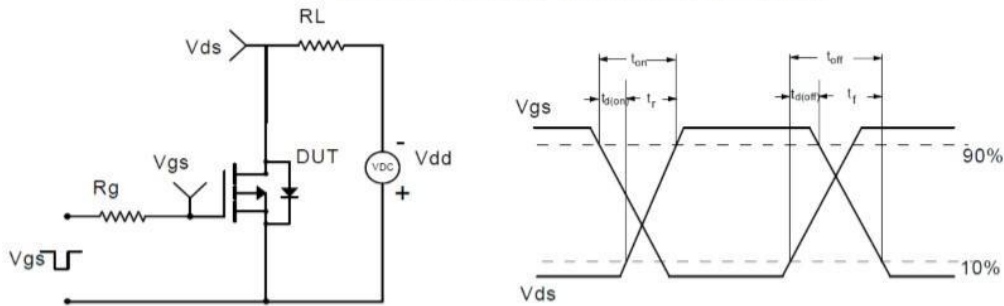


**Test Circuit**

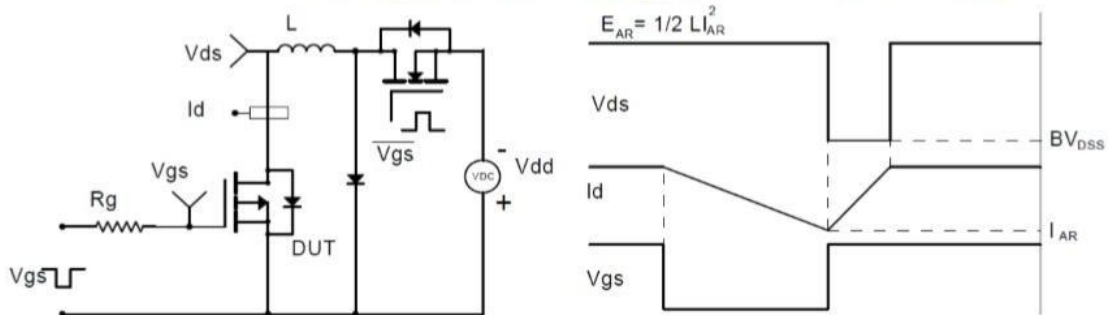
Gate Charge Test Circuit & Waveform



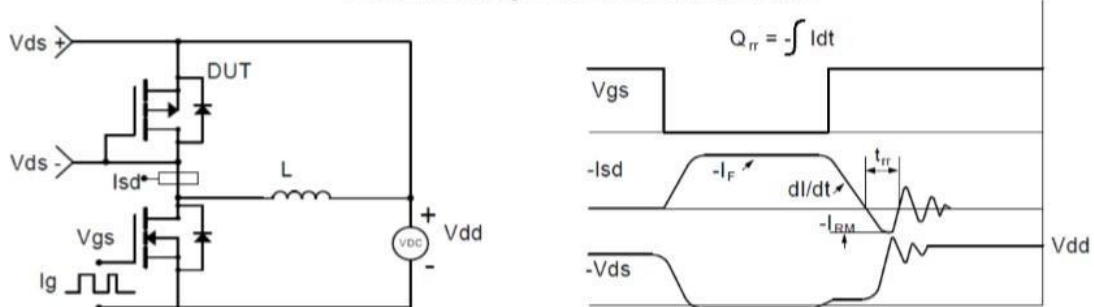
Resistive Switching Test Circuit & Waveforms

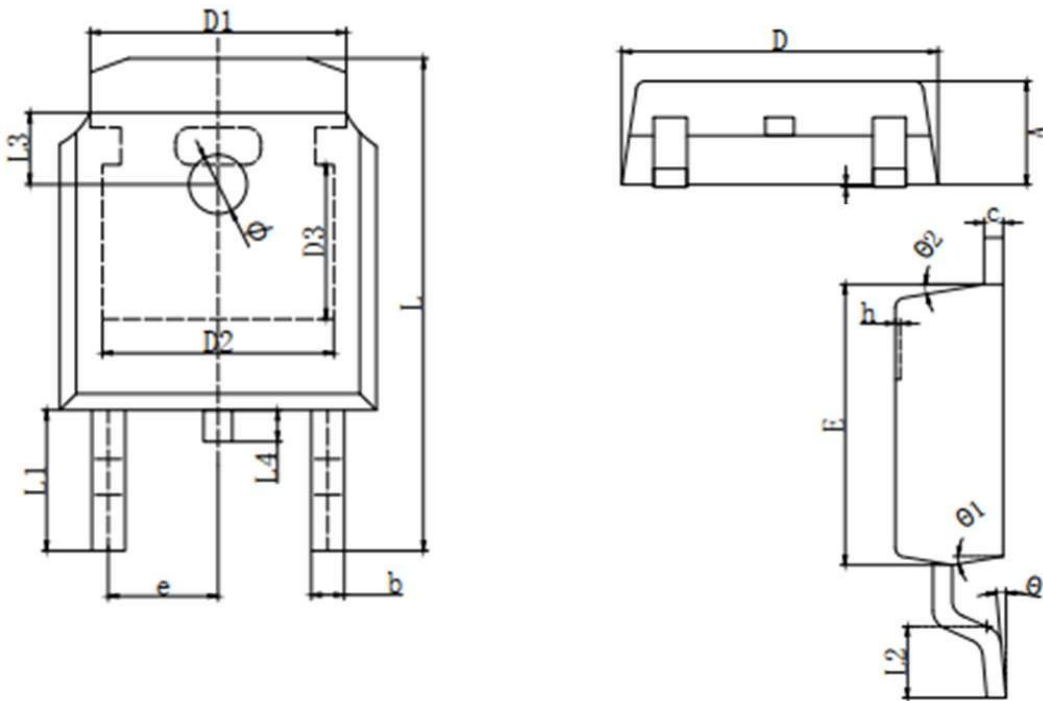


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



**TO-252 Package outline**


SYMBOL	MILLIMETER		SYMBOL	MILLIMETER	
	MIN	MAX		MIN	MAX
A	2.200	2.400	h	0.000	0.200
A1	0.000	0.127	L	9.900	10.30
b	0.640	0.740	L1	2.888 REF	
c	0.460	0.580	L2	1.400	1.700
D	6.500	6.700	L3	1.600 REF	
D1	5.334 REF		L4	0.600	1.000
D2	4.826 REF		$\phi$	1.100	1.300
D3	3.166 REF		$\theta$	0°	8°
E	6.000	6.200	$\theta 1$	9° TYP2	
e	2.286 TYP		$\theta 2$	9° TYP	